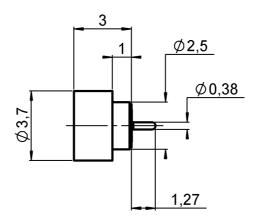
# HERMETIC STRAIGHT MALE RECEPTACLE SOLDER TYPE - FULL DETENT

R222.645.020

Series: SMP





Scale 1:1



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	DILVER P1 DILVER P1 - GLASS - -	GOLD 0.5 OVER NICKEL 2 GOLD 0.5 OVER NICKEL 2 -
-	-	-

**Issue:** 0633 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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#### **PACKAGING**

Standard	Unit	Other
100	'W' option	Contact us

#### **SPECIFICATION**

#### **ELECTRICAL CHARACTERISTICS**

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-18} \;\; \text{GHz} \end{array}$ 

VSWR 1.15 + 0,0000 x F(GHz) Maxi Insertion loss 0.12  $\sqrt{F(GHz)}$  dB Max

Insertion loss RF leakage 0.12  $\sqrt{F(GHz)}$  dB Maxi -(GHz) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 Veff mini 5000 M $\Omega$  mini

#### **ENVIRONMENTAL**

Operating temperature -65/+165 ° C

Hermetic seal **10-8** Atm.cm3/s

Panel leakage

#### **OTHERS CHARACTERISTICS**

Assembly instruction

Others:

### **MECHANICAL CHARACTERISTICS**

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.8 N mini
N.cm mini

Recommended torque

Mating N.cm Panel nut N.cm

Mating life 100 Cycles mini

Weight **0,0848** g

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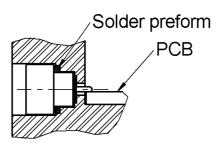
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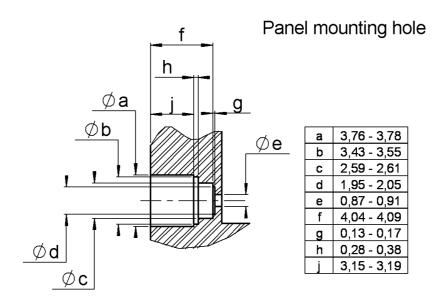
### HERMETIC STRAIGHT MALE RECEPTACLE **SOLDER TYPE - FULL DETENT**

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- Degrease and clean connector and box
- Solder the connector on the panel we advise SnAg4 Cu0.5, we recommand a low residue flux. Preheating at 100 °C. Take care not to exceed 260°C during solder operation
- 3. Solder the pin on the track we advise SnAg4 Cu0.5, we recommand a low residue flux. Preheating at 100 °C (only for ceramic substrate). Take care not to exceed 260°C during solder operation



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